<u>Technical Specifications for Table Top Oxygen Plasma</u> <u>Asher/Cleaner</u>

S.No	ltem	Description		Comply /	Catalogue
				Not	Page No.
				comply	
1)	Process Requirements/ Uses	1.1	 Primary Application and process capabilities Photoresist removal and stripping. Ashing of positive (Shipley) and pagative photoresists 		
			 Descum, prior to lift off of metals and passivation layers. Ashing of PMMA, PMGI and novolac based photoresist. 		
		1.2	Secondary Application		
			 Surface cleaning as part of the photolithographic process after the wet development of photoresist. Plasma Treatment for Surface Modifications. 		
		1.3	Substrate Size		
			Substrate size: small pieces 10 mmx10 mm to 100mmx100mm (4 inch wafer). Product yield: 1 wafer/run for 4 inch.		
2)	Power Supply	2.1	RF Power Source		
	Module		RF generator & Matching network (automatic type). Continuously adjustable, 1W- 150W (@13.56		
			MHz).		
			Digital RF power meter, RF cable kit desirable.		
			Power Supply: 220-230 V, Single Phase, 50-60 Hz		
3)	Process chamber	3.1	Chamber Size: suitable for 4 inch wafer processing.		
		3.2	Chamber Material: Quartz with chamber rear walls of Aluminum or SS. Quartz plate sample		

			holder suitable for 4 inch wafer.	
		3.3	Chamber Door: Compatible for 4" Silicon wafer	
			processing.	
			Port: View port is desirable.	
4)	Vacuum	4.1	Vacuum Pump: Suitable Dry Pump.	
	Module	4.2	Base Pressure: 0.1 mbar	
		4.3	Operating Pressure: 0.6 to 2 mbar	
		4.4	Vacuum Gauge: Suitable Vacuum Gauge	
			desirable.	
		4.5	Pumping port with Chamber Isolation valve	
			during the venting required.	
5)	Gases	5.1	The system shall support two process gases.	
			These should include oxygen and Argon.	
			Purge & Vent: Nitrogen	
		5.2	Gas Flow Rate:	
			Oxygen O₂: MFC (0-100 sccm).	
			Argon Ar: MFC (0-100 sccm).	
			Nitrogen: Flow meter, Desirable.	
		5.3	Proper venting arrangement using nitrogen gas	
			should be provided.	
		5.4	Pneumatically operated or Solenoid valves are	
			preferred.	
		5.5	Each process channel should include a	
			solenoid/pneumatic valve and standard Mass	
			tubing with 1/4" Standard connections.	
6)	6. System	6.1	Computer or Touchscreen based interactive	
-,	controls		suitable interface required.	
		6.2	Process control software	
	Hardware		User friendly recipe control. More than 10	
			euitable recipe storage required. Safety	
		63	Power control nanel	
			Emergency switch OFF facility should be	
			provided as safety measure.	

7)	Warranty	7.1	Two years' Standard warranty should be	
			provided Vender to provide standard warranty for a	
			neriod of 24 months	
			Vendor to give two Preventive Maintenance	
			Visits in the Warranty Period of the tool.	
			Vendor to provide all spares which will be	
			required during preventive maintenance for	
			the period of warranty.	
			The supplier should support the system	
			minimum for 10 years (post warranty) with all	
			spares and services.	
8)	Essential	8.1	The company should have supplied at least	
,	Requirements		three similar items to Indian/International	
	Requirements		academic and other Govt. of India R&D	
			organizations in the last (5 or 10) years, and	
			the proof of purchase order or performance	
			certificate should be provided	
9)	Onsite Process	9.1	The demo process of photoresist ashing and	
	Demonstration		cleaning should be carried out at the customer	
			SITE.	
		0.2	PR ash rate needs to be demonstrated.	
		9.2	Iraining of Personnel:	
(0)			User Training required	
10)	Mandatory		have authorized sales and service support in	
	documentatio		India.	
	n		i. Installation scheme showing the	
			physical space (footprint) of the	
			machine.	
			ii. System applications are to remove	
			resist and their residues, ashing, and	
			descum. System capabilities to be	
			listed and the list of recipes to be	
			provided.	
			iii. Cleaning procedure of the chamber	
			between the processes to be provided.	
			 iv. A compliance sheet must be provided by the vendor. 	
			v. System user manuals:	
			• User manuals.	
			System Hardware / Software	
			manuals.	
			Maintenance	

(Note: It is mandatory for the bidders to provide the compliance statement in tabular column format along with catalogue page number (comply/not comply) for the Above points with document proof as required. Failing which bidders will be technically disqualified)